# **Notice Inviting Quotation (E-Procurement mode)**

# INDIAN INSTITUTE OF TECHNOLOGY DELHI HAUZ KHAS, NEW DELHI-110016

Dated:06/04/2017

# Open Tender Notice No.IITD/BEEN(SP-961)/2017

Indian Institute of Technology Delhi is in the process of purchasing following item(s) as per details as given as under.

Details of the item	High precision table top probe station
Earnest Money Deposit to be submitted	Rs. 1 lakh
Warranty	2 Years
Performance security	NIL

Tender Documents may be downloaded from Central Public Procurement Portal <a href="http://eprocure.gov.in/eprocure/app">http://eprocure.gov.in/eprocure/app</a>. Aspiring Bidders who have not enrolled / registered in e-procurement should enroll / register before participating through the website <a href="http://eprocure.gov.in/eprocure/app">http://eprocure.gov.in/eprocure/app</a>. The portal enrolment is free of cost. Bidders are advised to go through instructions provided at 'Instructions for online Bid Submission '.

Tenderers can access tender documents on the website (For searching in the NIC site, kindly go to Tender Search option and type 'IIT'. Thereafter, Click on "GO" button to view all IIT Delhi tenders). Select the appropriate tender and fill them with all relevant information and submit the completed tender document online on the website <a href="http://eprocure.gov.in/eprocure/app">http://eprocure.gov.in/eprocure/app</a> as per the schedule given in the next page.

No manual bids will be accepted. All quotation (both Technical and Financial should be submitted in the E-procurement portal).

# **Schedule**

Name of Organization	Indian Institute of Technology Delhi	
Tender Type (Open/Limited/EOI/Auction/Single)	Open	
Tender Category (Services/Goods/works)	Goods	
Type/Form of Contract (Work/Supply/ Auction/Service/Buy/Empanelment/ Sell)	Buy	
Product Category (Civil Works/Electrical Works/Fleet Management/ Computer Systems)	Scientific equipment	
Source of Fund (Institute/Project)	Budget Code/ Project Code RP3303	
Is Multi Currency Allowed	YES (USD, INR)	
Date of Issue/Publishing	06/04/2017 (17:00Hrs)	
Document Download/Sale Start Date	06/04/2017 (17:00Hrs)	
Document Download/Sale End Date	27/04/2017 (11:00Hrs)	
Date for Pre-Bid Conference	N/A	
Venue of Pre-Bid Conference		
Last Date and Time for Uploading of Bids	27/04/2017 (11:00Hrs)	
Date and Time of Opening of Technical Bids	28/04/2017 (11:00Hrs)	
Tender Fee EMD	Rs. 0/- (For Tender Fee) Rs.1,00,000/-(For EMD) (To be paid through RTGS/NEFT. IIT Delhi Bank details are as under: Name of the Bank A/C : IITD Revenue Account SBI A/C No. :10773572622 Name of the Bank : State Bank of India, IIT Delhi, HauzKhas, New Delhi-110016 IFSC Code :SBIN0001077 MICR Code :110002156 Swift No. :SBININBB547 (This is mandatory that UTR Number is provided in the online quotation/bid. (Kindly refer to the UTR Column of the Declaration Sheet at Annexure-II)	
No. of Covers (1/2/3/4)	02	
Bid Validity days (180/120/90/60/30)	120days (From last date of opening of tender)	
Address for Communication	Madhusudan Singh, Department of Electrical Engineering, IIT Delhi, Hauz Khas, New Delhi – 110 016	
Contact No.	+91-11-2659-1063 (phone calls are discouraged, use email)	
Email Address	msingh@ee.iitd.ac.in	

Chairman Purchase Committee (Buyer Member)

#### **Instructions for Online Bid Submission:**

As per the directives of Department of Expenditure, this tender document has been published on the Central Public Procurement Portal (<u>URL:http://eprocure.gov.in/eprocure/app)</u>. The bidders are required to submit soft copies of their bids electronically on the CPP Portal, using valid Digital Signature Certificates. The instructions given below are meant to assist the bidders in registering on the CPP Portal, prepare their bids in accordance with the requirements and submitting their bids online on the CPP Portal.

More information useful for submitting online bids on the CPP Portal may be obtained at:

http://eprocure.gov.in/eprocure/app

#### **REGISTRATION**

- 1) Bidders are required to enroll on the e-Procurement module of the Central Public Procurement Portal (URL: <a href="http://eprocure.gov.in/eprocure/app">http://eprocure.gov.in/eprocure/app</a>) by clicking on the link "Click here to Enroll". Enrolment on the CPP Portal is free of charge.
- 2) As part of the enrolment process, the bidders will be required to choose a unique username and assign a password for their accounts.
- 3) Bidders are advised to register their valid email address and mobile numbers as part of the registration process. These would be used for any communication from the CPP Portal.
- 4) Upon enrolment, the bidders will be required to register their valid Digital Signature Certificate (Class II or Class III Certificates with signing key usage) issued by any Certifying Authority recognized by CCA India (e.g. Sify / TCS / nCode / eMudhra etc.), with their profile.
- 5) Only one valid DSC should be registered by a bidder. Please note that the bidders are responsible to ensure that they do not lend their DSCs to others which may lead to misuse.
- 6) Bidder then logs in to the site through the secured log-in by entering their userID / password and the password of the DSC / eToken.

#### **SEARCHING FOR TENDER DOCUMENTS**

- 1) There are various search options built in the CPP Portal, to facilitate bidders to search active tenders by several parameters. These parameters could include Tender ID, organization name, location, date, value, etc. There is also an option of advanced search for tenders, wherein the bidders may combine a number of search parameters such as organization name, form of contract, location, date, other keywords etc. to search for a tender published on the CPP Portal.
- 2) Once the bidders have selected the tenders they are interested in, they may download the required documents / tender schedules. These tenders can be moved to the respective 'My Tenders' folder. This would enable the CPP Portal to intimate the bidders through SMS / e-mail in case there is any corrigendum issued to the tender document.
- 3) The bidder should make a note of the unique Tender ID assigned to each tender, in case they want to obtain any clarification / help from the Helpdesk.

#### PREPARATION OF BIDS

- 1) Bidder should take into account any corrigendum published on the tender document before submitting their bids
- 2) Please go through the tender advertisement and the tender document carefully to understand the documents required to be submitted as part of the bid. Please note the number of covers in which the

bid documents have to be submitted, the number of documents - including the names and content of each of the document that need to be submitted. Any deviations from these may lead to rejection of the bid.

- 3) Bidder, in advance, should get ready the bid documents to be submitted as indicated in the tender document / schedule and generally, they can be in PDF / XLS / RAR / DWF formats. Bid documents may be scanned with 100 dpi with black and white option.
- 4) To avoid the time and effort required in uploading the same set of standard documents which are required to be submitted as a part of every bid, a provision of uploading such standard documents (e.g. PAN card copy, annual reports, auditor certificates etc.) has been provided to the bidders. Bidders can use "My Space" area available to them to upload such documents. These documents may be directly submitted from the "My Space" area while submitting a bid, and need not be uploaded again and again. This will lead to a reduction in the time required for bid submission process.

#### **SUBMISSION OF BIDS**

- 1) Bidder should log into the site well in advance for bid submission so that he/she upload the bid in time i.e. on or before the bid submission time. Bidder will be responsible for any delay due to other issues.
- 2) The bidder has to digitally sign and upload the required bid documents one by one as indicated in the tender document.
- 3) Bidder has to select the payment option as "on-line" to pay the tender fee / EMD as applicable and enter details of the instrument. Whenever, EMD / Tender fees is sought, bidders need to pay the tender fee and EMD separately on-line through RTGS (Refer to Schedule, Page No.2).
- 4) A standard BoQ format has been provided with the tender document to be filled by all the bidders. Bidders are requested to note that they should necessarily submit their financial bids in the format provided and no other format is acceptable. Bidders are required to download the BoQ file, open it and complete the white colored (unprotected) cells with their respective financial quotes and other details (such as name of the bidder). No other cells should be changed. Once the details have been completed, the bidder should save it and submit it online, without changing the filename. If the BoQ file is found to be modified by the bidder, the bid will be rejected.

OR

In some cases Financial Bids can be submitted in PDF format as well (in lieu of BOQ).

- 5) The server time (which is displayed on the bidders' dashboard) will be considered as the standard time for referencing the deadlines for submission of the bids by the bidders, opening of bids etc. The bidders should follow this time during bid submission.
- 6) All the documents being submitted by the bidders would be encrypted using PKI encryption techniques to ensure the secrecy of the data. The data entered cannot be viewed by unauthorized persons until the time of bid opening. The confidentiality of the bids is maintained using the secured Socket Layer 128 bit encryption technology. Data storage encryption of sensitive fields is done.
- 7) The uploaded tender documents become readable only after the tender opening by the authorized bid openers.
- 8) Upon the successful and timely submission of bids, the portal will give a successful bid submission message & a bid summary will be displayed with the bid no. and the date & time of submission of the bid with all other relevant details.
- 9) Kindly add scanned PDF of all relevant documents in a single PDF file of compliance sheet.

#### ASSISTANCE TO BIDDERS

- 1) Any queries relating to the tender document and the terms and conditions contained therein should be addressed to the Tender Inviting Authority for a tender or the relevant contact person indicated in the tender.
- 2) Any queries relating to the process of online bid submission or queries relating to CPP Portal in general may be directed to the 24x7 CPP Portal Helpdesk. The contact number for the helpdesk is 1800 233 7315.

#### **General Instructions to the Bidders**

- 1) The tenders will be received online through portal <a href="http://eprocure.gov.in/eprocure/app">http://eprocure.gov.in/eprocure/app</a>. In the Technical Bids, the bidders are required to upload all the documents in .pdf format.
- 2) Possession of a Valid Class II/III Digital Signature Certificate (DSC) in the form of smart card/e-token in the company's name is a prerequisite for registration and participating in the bid submission activities through https://eprocure.gov.in/eprocure/app. Digital Signature Certificates can be obtained from the authorized certifying agencies, details of which are available in the web site https://eprocure.gov.in/eprocure/app under the link "Information about DSC".
- 3) Tenderer are advised to follow the instructions provided in the 'Instructions to the Tenderer for the e-submission of the bids online through the Central Public Procurement Portal for e Procurement at https://eprocure.gov.in/eprocure/app.

### Department of Electrical Engineering Indian Institute of Technology HauzKhas, New Delhi-110 016

#### **NOTICE INVITING QUOTATIONS**

Dated: 06/04/2017

Subject: High precision table top probe station

#### **Invitation for Tender Offers**

Indian Institute of Technology Delhi invites online Bids (Technical bid and Commercial bid) from eligible and experienced OEM (Original Equipment Manufacturer) OR OEM Authorized Dealer for supply, installation & integration of a high precision table top probe station with (warranty period as stated at page #1 of this tender) on-site comprehensive warranty from the date of receipt of the material as per terms & conditions specified the tender document, which is available on **CPP Portal** in http://eprocure.gov.in/eprocure/app

Every claim of compliance to the specifications should be accompanied with quantitative evidence of that claim, along with references in scientific data, and / or (preferably) scientific literature, that are exemplars of that claim for the specific tool or tool component that you are bidding. Merely writing, "Yes" will not be sufficient, given the complexity of this tool. Compliance will be judged on the basis of the evidence you provide, and the body of literature referencing your bid tool and configuration, and not mere unsupported statements. All documentation about similar installs done at least 1 year prior to the bid by the vendor must correspond to a configuration either identical to the one required in this tender, or vastly similar, with a due list of differences noted explicitly in each case.

#### **TECHNICAL SPECIFICATION:**

Sl.	Technical Specifications	
No.		
1.	High precision table top probe station for DC IV/CV electrical characterization of devices on substrates ranging between 0.5"x0.5" to 6"x6".	
	Footprint (max) of the entire assembled system: 1100 mm (x:width) x800 mm (y:depth) x 1000 mm (z:height). If more space is needed, the bidder must explicitly note that in their bid and remain ready to provide additional related specs justifying the additional space.	
	The system design should include future expansion possibility so that all optional items listed in this tender document can be added later without the base system needing to be moved dismantled, or significantly interrupted in its existing operation in any manner, subject to the constraints stated in this tender document.	
	In case of any optional item needing an upgrade to the base configuration, the financial quote	

	should include all costs corresponding to the upgrade. All incompatibilities with other listed		
	options should be explicitly noted in such case.		
2.	Vacuum tri-axial chuck. X-Y movement must encompass at least 150 mm x 150 mm with better than a		
	least 5 micron resolution. Z movement should be adjustable up to 10 mm and load stroke of up to 3		
	mm. Theta movement: 360 degrees. Planarity of chuck should be +/- 3 microns or better. More than 88		
2	mm rollout chuck stage for easy wafer loading.		
3.	Platen movement should be manual. Course and fine platen lift up to to 40 mm with contact /		
4.	separation stroke of 200 microns with a repeatability of at least 1 micron or better.		
4.	Magnetic base probe micropositioners (4). Minimum probing pad size: 5 micron x 5 micron. Probe positioners must have a three dimensional movement of at least 12.5 mm in each cardinal direction.		
	Feature resolution should be 2 microns or better. All needed triaxprobe arms and triaxial cables must be		
	included.		
5.	Noise floor: The instrument must not interpose a noise floor any higher than that of a Keithley 2450		
J.	(10 fA) or that of a semiconductor parameter analyzer (fA), voltages (mV) and capacitance (pF) or		
	better. It should use		
6.	High resolution stereo-zoom microscope with large working distance (20x-300x) should be included.		
7.	All tools needed for setup, use, and maintenance should be provided.		
8.	An electronic copy of the operating manual should be provided.		
9.	Comprehensive warranty for 2 years must be included. Additional years' AMC quote should be		
	provided separately. Shipping terms must be door to door (the site of the installation is at second floor		
	and not easily accessible via ramp or elevator at present.		
Sl.	Technical Specifications		
No.			
1.	High precision table top probe station for DC IV/CV electrical characterization of devices on substrates		
	ranging between 0.5"x0.5" to 6"x6".		
	Footprint (max) of the entire assembled system: 1100 mm (x:width) x800 mm (y:depth) x 1000 mm		
	(z:height). If more space is needed, the bidder must explicitly note that in their bid and remain ready to		
	provide additional related specs justifying the additional space.		
	The system design should include future expansion possibility so that all optional items listed in		
	this tender document can be added later without the base system needing to be moved,		
	dismantled, or significantly interrupted in its existing operation in any manner, subject to the		
	constraints stated in this tender document.		
	In case of any optional item needing an upgrade to the base configuration, the financial quote		
	should include all costs corresponding to the upgrade. All incompatibilities with other listed		
	options should be explicitly noted in such case.		
2.	Vacuum tri-axial chuck. X-Y movement must encompass at least 150 mm x 150 mm with better than at		
	least 5 micron resolution. Z movement should be adjustable up to 10 mm and load stroke of up to 3		
	mm. Theta movement: 360 degrees. Planarity of chuck should be +/- 3 microns or better. More than 88		
	mm rollout chuck stage for easy wafer loading.		
3.	Platen movement should be manual. Course and fine platen lift up to to 40 mm with contact /		
4.	separation stroke of 200 microns with a repeatability of at least 1 micron or better.  Magnetic base probe micropositioners (4). Minimum probing pad size: 5 micron x 5 micron. Probe		

	positioners must have a three dimensional movement of at least 12.5 mm in each cardinal direction.
	Feature resolution should be 2 microns or better. All needed triaxprobe arms and triaxial cables must be
	included.
5.	Noise floor: The instrument must not interpose a noise floor any higher than that of a Keithley 2450
	(10 fA) or that of a semiconductor parameter analyzer (fA), voltages (mV) and capacitance (pF) or
	better. It should use
6.	High resolution stereo-zoom microscope with large working distance (20x-300x) should be included.
7.	All tools needed for setup, use, and maintenance should be provided.
8.	An electronic copy of the operating manual should be provided.
9.	Comprehensive warranty for 2 years must be included. Additional years' AMC quote should be
	provided separately. Shipping terms must be door to door (the site of the installation is at second floor
	and not easily accessible via ramp or elevator at present.

Sl. No.	List of optional items	
1.	Motorized chuck movement.	
2.	Probe card holder upgrade.	
3.	Eight micro positioners for simultaneous use.	
4.	25 tungsten probe tips with 6 micron tip radius.	
5.	25 tungsten probe tips with 1.2 micron tip radius.	
6.	25 tungsten probe tips with 2.4 micron tip radius.	
7.	Dark enclosure to enable testing under dark and to provide EMF shielding with feedthroughs: triax to coax (at least 4).	
	Four micro positioners with force/sense cables to feedthroughs.	
8.	Vibration isolation stage supporting the whole setup. Further, gas lines for clean dry air should be provided along with pressure specs.	
9.	High magnification turret microscope in-lieu of stereomicroscope with objectives: 2.5x, 10x, 20x, 50x. The 50x objective should support a working distance of at least 10 mm, with provision for external fiber coupling with a user supplied beam splitter.	
10.	1080p resolution camera attachment for the microscope with software.	
11.	A high-speed c-mount camera (EM-CCD camera,sCMOS or equivalent) with software should be quoted.	
12.	12. Feedthroughs: a) coax to coax (2), b) multimode optical fibers SMA905 (1), c) multimode of fiber for coupling external light source (1), d) 1 thermal (Pt/Si diode) sensor to shielded twiste cable, e) camera o/p to HDMI, f) USB-A M/M to USB-A M/M. Additionally, two blanks for integration of additional feedthroughs should be provided. If any / all of these feedthroughs a provided, the bidder must provide an easily replaceable light tight blank for the m feedthroughs, and provide a link to the specific feedthrough available from another source	

bidder must thus make certain that the user does not need to drill a hole in the enclosure to install
additional feedthroughs.

13. Vacuum pump and any needed vacuum lines for the chuck. Alternately, pressure specs for vacuum lines must be provided in addition to the lines.

A complete set of tender documents\* may be Download by prospective bidder free of cost from the website <a href="http://eprocure.gov.in/eprocure/app">http://eprocure.gov.in/eprocure/app</a>. Bidder has to make payment of requisite fees (i.e. Tender fees (if any) and EMD) online through RTGS/NEFT only.

# **Terms & Conditions Details**

Sl.No.	Specification
1.	<b>Due date</b> : The tender has to be submitted on-line before the due date. The offers received after the
	due date and time will not be considered. No manual bids will be considered.
2.	<b>Preparation of Bids</b> : The offer/bid should be submitted in two bid systems (i.e.) Technical bid and financial bid. The technical bid should consist of all technical details along with commercial terms and conditions. Financial bid should indicate item wise price for the items mentioned in the technical bid in the given format i.e Financial Bids to be submitted in PDF format. The Technical bid and the financial bid should be submitted Online.
3.	<b>EMD</b> ( <b>if applicable</b> ): The tenderer should submit an EMD amount through RTGS/NEFT. The Technical Bid without EMD would be considered as UNRESPONSIVE and will not be accepted. The EMD will be refunded without any interest to the unsuccessful bidders after the award of contract. Refer to Schedule (at page 1 of this document) for its actual place of submission.
4.	<b>Refund of EMD</b> : The EMD will be returned to unsuccessful Tenderer only after the Tenders are finalized. In case of successful Tenderer, it will be retained till the successful and complete installation of the equipment.
5.	<b>Opening of the tender</b> : The online bid will be opened by a committee duly constituted for this purpose. Online bids (complete in all respect) received along with EMD (if any) will be opened as mentioned at "Annexure: Schedule" in presence of bidders representative if available. Only one representative will be allowed to participate in the tender opening. Bid received without EMD (if present) will be rejected straight way. The technical bid will be opened online first and it will be examined by a technical committee (as per specification and requirement). The financial offer/bid will be opened only for the offer/bid which technically meets all requirements as per the specification, and will be opened in the presence of the vendor's representatives subsequently for further evaluation. The bidders if interested may participate on the tender opening Date and Time. The bidder should produce authorization letter from their company to participate in the tender opening.
6.	<b>Acceptance/ Rejection of bids:</b> The Committee reserves the right to reject any or all offers without assigning any reason.
7.	Pre-qualification criteria:  (i) Bidders should be the manufacturer / authorized dealer. Letter of Authorization from original equipment manufacturer (OEM) on the same and specific to the tender should be enclosed.  (ii) An undertaking from the OEM is required stating that they would facilitate the bidder on a regular basis with technology/product updates and extend support for the warranty as well. (Ref. Annexure-II)
	<ul> <li>(iii) OEM should be internationally reputed Branded Company.</li> <li>(iv) Non-compliance of tender terms, non-submission of required documents, lack of clarity of the specifications, contradiction between bidder specification and supporting documents etc. may lead to rejection of the bid.</li> <li>(v) In the tender, either the Indian agent on behalf of the Principal/OEM or Principal/OEM itself can bid but both cannot bid simultaneously for the same item/product in the same tender.</li> <li>(vi) If an agent submits bid on behalf of the Principal/OEM, the same agent shall not submit a bid on behalf of another Principal/OEM in the same tender for the same item/product.</li> </ul>
8.	<b>Performance Security</b> : The supplier shall require to submit the performance security in the form of irrevocable bank guarantee issued by any Indian Nationalized Bank for an amount which is stated at page #1 of the tender document within 21 days from the date of receipt of the purchase order/LC and should be kept valid for a period of 60 days beyond the date of completion of warranty period.
9.	Force Majeure: The Supplier shall not be liable for forfeiture of its performance security,

liquidated damages or termination for default, if and to the extent that, it's delay in performance or other failure to perform its obligations under the Contract is the result of an event of Force Majeure. For purposes of this Clause, "Force Majeure" means an event beyond the control of the Supplier and not involving the Supplier's fault or negligence and not foreseeable. Such events may include, but are not limited to, acts of the Purchaser either in its sovereign or contractual capacity, wars or revolutions, fires, floods, epidemics, quarantine restrictions and freight embargoes. If a Force Majeure situation arises, the Supplier shall promptly notify the Purchaser in writing of such conditions and the cause thereof. Unless otherwise directed by the Purchaser in writing, the Supplier shall continue to perform its obligations under the Contract as far as is reasonably practical, and shall seek all reasonable alternative means for performance not prevented by the Force Majeure event. 10. Risk Purchase Clause: In event of failure of supply of the item/equipment within the stipulated delivery schedule, the purchaser has all the right to purchase the item/equipment from the other source on the total risk of the supplier under risk purchase clause. 11. Packing Instructions: Each package will be marked on three sides with proper paint/indelible ink, the following: i. Item Nomenclature ii. Order/Contract No. iii. Country of Origin of Goods iv. Supplier's Name and Address v. Consignee details vi. Packing list reference number 12. **Delivery and Documents:** Delivery of the goods should be made within a maximum of 08 to 16 weeks from the date of placement of purchase order and the opening of LC. Within 24 hours of shipment, the supplier shall notify the purchaser and the insurance company by cable/telex/fax/e mail the full details of the shipment including contract number, railway receipt number/ AAP etc. and date, description of goods, quantity, name of the consignee, invoice etc. The supplier shall mail the following documents to the purchaser with a copy to the insurance company: 1. 4 Copies of the Supplier invoice showing contract number, goods' description, quantity 2. unit price, total amount; 3. Insurance Certificate if applicable; 4. Manufacturer's/Supplier's warranty certificate; 5. Inspection Certificate issued by the nominated inspection agency, if any 6. Supplier's factory inspection report; and 7. Certificate of Origin (if possible by the beneficiary); 8. Two copies of the packing list identifying the contents of each package. The above documents should be received by the Purchaser before arrival of the Goods (except where the Goods have been delivered directly to the Consignee with all documents) and, if not received, the Supplier will be responsible for any consequent expenses. 13. **Delayed delivery:** If the delivery is not made within the due date for any reason, the Committee will have the right to impose penalty 1% per week and the maximum deduction is 10% of the contract value / price. 14. **Prices**: The price should be quoted in net per unit (after breakup) and must include all packing and delivery charges. The offer/bid should be exclusive of taxes and duties, which will be paid by the purchaser as applicable. However the percentage of taxes & duties shall be clearly indicated.

The price should be quoted without custom duty and excise duty, since IIT Delhi is exempted from payment of Excise Duty and is eligible for concessional rate of custom duty. Necessary

certificate will be issued on demand.

In case of imports, the price should be quoted on FOB Basis only. Under special circumstances (eg. perishable chemicals), when the item is imported on CIF/CIP, please indicate CIF/CIP charges separately upto IIT Delhi indicating the mode of shipment. IIT Delhi will make necessary arrangements for the clearance of imported goods at the Airport/Seaport. Hence the price should not include the above charges.

15. **Notices:**For the purpose of all notices, the following shall be the address of the Purchaser and Supplier.

Purchaser: Madhusudan Singh, Department of Electrical Engineering Indian Institute of Technology HauzKhas, New Delhi - 110016.

**Supplier:** (To be filled in by the supplier)

(All supplier's should submit its supplies information as per Annexure-II).

- 16. **Progress of Supply**: Wherever applicable, supplier shall regularly intimate progress of supply, in writing, to the Purchaser as under:
  - 1. Quantity offered for inspection and date;
  - 2. Quantity accepted/rejected by inspecting agency and date;
  - 3. Quantity dispatched/delivered to consignees and date;
  - 4. Quantity where incidental services have been satisfactorily completed with date;
  - 5. Quantity where rectification/repair/replacement effected/completed on receipt of any communication from consignee/Purchaser with date;
  - 6. Date of completion of entire Contract including incidental services, if any; and
  - 7. Date of receipt of entire payments under the Contract (In case of stage-wise inspection, details required may also be specified).
- 17. **Inspection and Tests:** Inspection and tests prior to shipment of Goods and at final acceptance are as follows:
  - After the goods are manufactured and assembled, inspection and testing of the goods shall be carried out at the supplier's plant by the supplier, prior to shipment to check whether the goods are in conformity with the technical specifications attached to the purchase order. Manufacturer's test certificate with data sheet shall be issued to this effect and submitted along with the delivery documents. The purchaser shall be present at the supplier's premises during such inspection and testing if need is felt. The location where the inspection is required to be conducted should be clearly indicated. The supplier shall inform the purchaser about the site preparation, if any, needed for installation of the goods at the purchaser's site at the time of submission of order acceptance.
  - The acceptance test will be conducted by the Purchaser, their consultant or other such person nominated by the Purchaser at its option after the equipment is installed at purchaser's site in the presence of supplier's representatives. The acceptance will involve trouble free operation and ascertaining conformity with the ordered specifications and quality. There shall not be any additional charges for carrying out acceptance test. No malfunction, partial or complete failure of any part of the equipment is expected to occur. The Supplier shall maintain necessary log in respect of the result of the test to establish to the entire satisfaction of the Purchaser, the successful completion of the test specified.
  - In the event of the ordered item failing to pass the acceptance test, a period not exceeding one weeks will be given to rectify the defects and clear the acceptance test, failing which the

	Purchaser reserve the right to get the equipment replaced by the Supplier at no extra cost to the
	Purchaser.
	• Successful conduct and conclusion of the acceptance test for the installed goods and equipment
10	shall also be the responsibility and at the cost of the Supplier.
18.	<b>Resolution of Disputes</b> : The dispute resolution mechanism to be applied pursuant shall be as
	follows:
	• In case of Dispute or difference arising between the Purchaser and a domestic supplier relating to any matter arising out of or connected with this agreement, such disputes or difference shall be
	settled in accordance with the Indian Arbitration& Conciliation Act, 1996, the rules there under
	and any statutory modifications or re-enactments thereof shall apply to the arbitration proceedings.
	The dispute shall be referred to the Director, Indian Institute of Technology (IIT) Delhi and if he is
	unable or unwilling to act, to the sole arbitration of some other person appointed by him willing to
	act as such Arbitrator. The award of the arbitrator so appointed shall be final, conclusive and
	binding on all parties to this order.
	• In the case of a dispute between the purchaser and a Foreign Supplier, the dispute shall be settled
	by arbitration in accordance with provision of sub-clause (a) above. But if this is not acceptable to
	the supplier then the dispute shall be settled in accordance with provisions of UNCITRAL (United
	Nations Commission on International Trade Law) Arbitration Rules.
	• The venue of the arbitration shall be the place from where the order is issued.
19.	Applicable Law: The place of jurisdiction would be New Delhi (Delhi) INDIA.
20.	Right to Use Defective Goods
	If after delivery, acceptance and installation and within the guarantee and warranty period, the
	operation or use of the goods proves to be unsatisfactory, the Purchaser shall have the right to continue to operate or use such goods until rectifications of defects, errors or omissions by repair or
	by partial or complete replacement is made without interfering with the Purchaser's operation.
21.	Supplier Integrity
21.	The Supplier is responsible for and obliged to conduct all contracted activities in accordance with
	the Contract using state of the art methods and economic principles and exercising all means
	available to achieve the performance specified in the contract.
22.	Training
	The Supplier is required to provide training to the designated Purchaser's technical and end user
	personnel to enable them to effectively operate the total equipment.
23.	Installation & Demonstration
	The supplier is required to done the installation and demonstration of the equipment within one
	month of the arrival of materials at the IITD site of installation, otherwise the penalty clause will be the same as per the supply of materials.
	the same as per the suppry of materials.
	In case of any mishappening/damage to equipment and supplies during the carriage of supplies
	from the origin of equipment to the installation site, the supplier has to replace it with new
	equipment/supplies immediately at his own risk. Supplier will settle his claim with the insurance
	company as per his convenience. IITD will not be liable to any type of losses in any form.
24.	<b>Insurance:</b> For delivery of goods at the purchaser's premises, the insurance shall be obtained by the
	supplier in an amount equal to 110% of the value of the goods from "warehouse to warehouse"
	(final destinations) on "All Risks" basis including War Risks and Strikes. The insurance shall be
	valid for a period of not less than 3 months after installation and commissioning. <b>In case of orders</b>
	placed on FOB/FCA basis, the purchaser shall arrange Insurance. If orders placed on
25.	CIF/CIP basis, the insurance should be up to IIT Delhi. Incidental services: The incidental services also include:
23.	
	• Furnishing of 01 set of detailed operations & maintenance manual.

	• Arranging the shifting/moving of the item to their location of final installation within IITD premises at the cost of Supplier through their Indian representatives.
26.	<ul> <li>Warranty: <ol> <li>Warranty period shall be (as stated at page #2 of this tender) from date of installation of Goods at the IITD site of installation. The Supplier shall, in addition, comply with the performance and/or consumption guarantees specified under the contract. If for reasons attributable to the Supplier, these guarantees are not attained in whole or in part, the Supplier shall at its discretion make such changes, modifications, and/or additions to the Goods or any part thereof as may be necessary in order to attain the contractual guarantees specified in the Contract at its own cost and expense and to carry out further performance tests. The warranty should be comprehensive on site.</li> <li>The Purchaser shall promptly notify the Supplier in writing of any claims arising under this warranty. Upon receipt of such notice, the Supplier shall immediately within in 02 days arrange to repair or replace the defective goods or parts thereof free of cost at the ultimate destination. The Supplier shall take over the replaced parts/goods at the time of their replacement. No claim whatsoever shall lie on the Purchaser for the replaced parts/goods thereafter. The period for correction of defects in the warranty period is 02 days. If the supplier having been notified fails to remedy the defects within 02 days, the purchaser may proceed to take such remedial action as may be necessary, at the supplier's risk and expenses and without prejudice to any other rights, which the purchaser may have against the supplier under the contract.</li> <li>The warranty period should be clearly mentioned. The maintenance charges (AMC) under different schemes after the expiry of the warranty should also be mentioned. The comprehensive warranty will commence from the date of the satisfactory installation/commissioning of the equipment against the defect of any manufacturing, workmanship and poor quality of the components.</li> <li>After the warranty period is over, Annual Maintenance Contract (AMC)/Comprehensive Maintenance</li></ol></li></ul>
27.	charges will not be included in computing the total cost of the equipment.  Governing Language  The contract shall be written in English language. English language version of the Contract shall govern its interpretation. All correspondence and other documents pertaining to the Contract, which
	are exchanged by the parties, shall be written in the same language.
28.	Applicable Law The Contract shall be interpreted in accordance with the laws of the Union of India and all disputes shall be subject to place of jurisdiction.
29.	<ul> <li>Notices</li> <li>Any notice given by one party to the other pursuant to this contract/order shall be sent to the other party in writing or by cable, telex, FAX or e mail and confirmed in writing to the other party's address.</li> <li>A notice shall be effective when delivered or on the notice's effective date, whichever is later.</li> </ul>
30.	Taxes Suppliers shall be entirely responsible for all taxes, duties, license fees, octroi, road permits, etc., incurred until delivery of the contracted Goods to the Purchaser. However, VAT in respect of the transaction between the Purchaser and the Supplier shall be payable extra, if so stipulated in the order.
31.	Duties IIT Delhi is exempted from paying custom duty under notification No.51/96 (partially or full) and

necessary "Custom Duty Exemption Certificate" can be issued after providing following information and Custom Duty Exemption Certificate will be issued to the shipment in the name of the Institute, (no certificate will be issued to third party): The procured product should be used for teaching, scientific and research work only. a) Shipping details i.e. Master Airway Bill No. and House Airway No. (if exists)

- b) Forwarder details i.e. Name, Contact No., etc.

IIT Delhi is exempted from paying Excise Duty and necessary Excise Duty Exemption Certificate will be provided for which following information are required.

- b) Quotation with details of Basic Price, Rate, Tax & Amount on which ED is applicable
- c) Supply Order Copy
- d) Proforma-Invoice Copy.
- 32. Agency Commission: Agency commission if any will be paid to the Indian agent in Rupees on receipt of the equipment and after satisfactory installation. Agency Commission will not be paid in foreign currency under any circumstances. The details should be explicitly shown in Tender even in case of Nil commission. The tenderer should indicate the percentage of agency commission to be paid to the Indian agent.

#### 33. **Payment:**

- For imported items Payment will be made through irrevocable Letter of Credit (LC). Letter of Credit (LC) will be established in favour of foreign Supplier after the submission of performance security. The letter of credit (LC) will be established on the exchange rates as applicable on the date of establishment. For Imports, LC will be opened for 100% FOB/CIF value. 80% of the LC amount shall be released on presentation of complete and clear shipping documents and 20% of the LC amount shall be released after the installation and demonstration of the equipment at the INST site of installation in faultless working condition for period of 60 days from the date of the satisfactory installation and subject to the production of unconditional performance bank guarantee as specified in Clause 8 of tender terms and conditions.
- (ii) For Indigenous supplies, 100% payment shall be made by the Purchaser against delivery, inspection, successful installation, commissioning and acceptance of the equipment at IITD in good condition and to the entire satisfaction of the Purchaser and on production of unconditional performance bank guarantee as specified in Clause 9 of tender terms and conditions.
- (iii) Indian Agency commission (IAC), if any shall be paid after satisfactory installation & commissioning of the goods at the destination at the exchange rate prevailing on the date of negotiation of LC documents, subject to DGS&D registration for restricted items.
- (iv) All the bank charges within India will be borne by the Institute and outside India will be borne by the Supplier.
- User list: Brochure detailing technical specifications and performance, list of industrial and 34. educational establishments where the items enquired have been supplied must be provided. (Ref. Annexure-III)

#### 35. **Manuals and Drawings**

- Before the goods and equipment are taken over by the Purchaser, the Supplier shall supply operation and maintenance manuals. These shall be in such details as will enable the Purchaser to operate, maintain, adjust and repair all parts of the works as stated in the specifications.
- The Manuals shall be in the ruling language (English) in such form and numbers as stated in the contract.
- (iii) Unless and otherwise agreed, the goods equipment shall not be considered to be completed for the purposes of taking over until such manuals and drawing have been supplied to the Purchaser.

Application Specialist: The Tenderer should mention in the Techno-Commercial bid the 36. availability and names of Application Specialist and Service Engineers in the nearest regional office. (Ref. to Annexure-III) 37. **Site Preparation**: The supplier shall inform to the Institute about the site preparation, if any, needed for the installation of equipment, immediately after the receipt of the purchase order. The supplier must provide complete details regarding space and all the other infrastructural requirements needed for the equipment, which the Institute should arrange before the arrival of the equipment to ensure its timely installation and smooth operation thereafter. The supplier shall visit the Institute and see the site where the equipment is to be installed and may offer his advice and render assistance to the Institute in the preparation of the site and other pre-installation requirements. 38. **Spare Parts** The Supplier may be required to provide any or all of the following materials, notifications, and information pertaining to spare parts manufactured or distributed by the Supplier: ii. Such spare parts as the Purchaser may elect to purchase from the Supplier, providing that this election shall not relieve the Supplier of any warranty obligations under the Contract; and iii. In the event of termination of production of the spare parts: iv. Advance notification to the Purchaser of the pending termination, in sufficient time to permit the Purchaser to procure needed requirements; and v. Following such termination, furnishing at no cost to the Purchaser, the blueprints, drawings and specifications of the spare parts, if requested. Supplier shall carry sufficient inventories to assure ex-stock supply of consumable spares for the Goods, such as gaskets, plugs, washers, belts etc. Other spare parts and components shall be supplied as promptly as possible but in any case within six months of placement of order. 39. **Defective Equipment**: If any of the equipment supplied by the Tenderer is found to be substandard, refurbished, un-merchantable or not in accordance with the description/specification or otherwise faulty, the committee will have the right to reject the equipment or its part. The prices of such equipment shall be refunded by the Tenderer with 18% interest if such payments for such equipment have already been made. All damaged or unapproved goods shall be returned at suppliers cost and risk and the incidental expenses incurred thereon shall be recovered from the supplier. Defective part in equipment, if found before installation and/or during warranty period, shall be replaced within 45 days on receipt of the intimation from this office at the cost and risk of supplier including all other charges. In case supplier fails to replace above item as per above terms & conditions, IIT Delhi may consider "Banning" the supplier. 40. **Termination for Default** The Purchaser may, without prejudice to any other remedy for breach of contract, by written notice of default sent to the Supplier, terminate the Contract in whole or part: If the Supplier fails to deliver any or all of the Goods within the period(s) specified in the order, or within any extension thereof granted by the Purchaser; or ii If the Supplier fails to perform any other obligation(s) under the Contract. iii If the Supplier, in the judgment of the Purchaser has engaged in corrupt or fraudulent practices in competing for or in executing the Contract. For the purpose of this Clause: "Corrupt practice" means the offering, giving, receiving or soliciting of anything of value to influence the action of a public official in the procurement process or in contract execution. ii. "Fraudulent practice" means a misrepresentation of facts in order to influence a procurement process or the execution of a contract to the detriment of the Borrower, and includes collusive practice among Bidders (prior to or after bid submission) designed to establish bid prices at artificial non-competitive levels and to deprive the

	Borrower of the benefits of free and open competition;"	
	• In the event the Purchaser terminates the Contract in whole or in part, the Purchaser may procure, upon such terms and in such manner, as it deems appropriate, Goods or Services similar to those undelivered, and the Supplier shall be liable to the Purchaser for any excess costs for such similar Goods or Services. However, the Supplier shall continue the performance of the Contract to the extent not terminated.	
41.	<b>Shifting</b> : After 1-2 years once our new Academic Block will be ready, the supplier has to shift and reinstall the instrument free of cost (if required).	
42.	<b>Downtime:</b> During the warranty period not more than 5% downtime will be permissible. For every day exceeding permissible downtime, penalty of 1/365 of the 5% FOB value will be imposed. Downtime will be counted from the date and time of the filing of complaint with in the business hours.	
43.	<b>Training of Personnel:</b> The supplier shall be required to undertake to provide the technical training to the personnel involved in the use of the equipment at the Institute premises, immediately after completing the installation of the equipment for a minimum period of one week at the supplier's cost.	
44.	<b>Disputes and Jurisdiction</b> : Any legal disputes arising out of any breach of contract pertaining to this tender shall be settled in the court of competent jurisdiction located within New Delhi.	
45.	<b>Compliancy certificate</b> : This certificate must be provided indicating conformity to the technical specifications. (Annexure-I)	
46.	"In case of CIF/CIP shipments, kindly provide the shipment information at least 2 days in advance before landing the shipment along with the documents i.e. invoice, packing list, forwarder Name, address, contact No. in India to save demurrage charges (imposed by Indian Customs). Otherwise these charges will be recovered from the supplier/Indian Agent."	

# **COMPLIANCE SHEET**

# TECHNICAL SPECIFICATION

Sl.	<b>Technical Specifications</b>	COMPLIANCE
No.		Y/N
1.	High precision table top probe station for DC IV/CV electrical characterization of devices on substrates ranging between 0.5"x0.5" to 6"x6".	
	Footprint (max) of the entire assembled system: 1100 mm (x:width) x800 mm (y:depth) x 1000 mm (z:height). If more space is needed, the bidder must explicitly note that in their bid and remain ready to provide additional related specs justifying the additional space.	
	The system design should include future expansion possibility so that all optional items listed in this tender document can be added later without the base system needing to be moved, dismantled, or significantly interrupted in its existing operation in any manner, subject to the constraints stated in this tender document.	
	In case of any optional item needing an upgrade to the base configuration, the financial quote should include all costs corresponding to the upgrade. All incompatibilities with other listed options should be explicitly noted in such case.	
2.	Vacuum tri-axial chuck. X-Y movement must encompass at least 150 mm x 150 mm with better than at least 5 micron resolution. Z movement should be adjustable up to 10 mm and load stroke of up to 3 mm. Theta movement: 360 degrees. Planarity of chuck should be +/- 3 microns or better. More than 88 mm rollout chuck stage for easy wafer loading.	
3.	Platen movement should be manual. Course and fine platen lift up to to 40 mm with contact / separation stroke of 200 microns with a repeatability of at least 1 micron or better.	
4.	Magnetic base probe micropositioners (4). Minimum probing pad size: 5 micron x 5 micron. Probe positioners must have a three dimensional movement of at least 12.5 mm in each cardinal direction. Feature resolution should be 2 microns or better. All needed triaxprobe arms and triaxial cables must be included.	
5.	Noise floor: The instrument must not interpose a noise floor any higher than that of a Keithley 2450 (10 fA) or that of a semiconductor parameter analyzer (fA), voltages (mV) and capacitance (pF) or better. It should use	
6.	High resolution stereo-zoom microscope with large working distance (20x-300x) should be included.	
7.	All tools needed for setup, use, and maintenance should be provided.	
8.	An electronic copy of the operating manual should be provided.	

9.	Comprehensive warranty for 2 years must be included. Additional years' AMC quote should be provided separately. Shipping terms must be door to door (the site of the installation is at second floor and not easily accessible via ramp or elevator at present.
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	Footprint (max) of the entire assembled system: 1100 mm (x:width) x800 mm (y:depth) x 1000 mm (z:height). If more space is needed, the bidder must explicitly note that in their bid and remain ready to provide additional related specs justifying the additional space.
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SI. No.  List of optional items  COMPLIANCE  Y/N  1. Motorized chuck movement.  2. Probe card holder upgrade.  3. Eight micro positioners for simultaneous use.  4. 25 tungsten probe tips with 6 micron tip radius.  5. 25 tungsten probe tips with 1.2 micron tip radius.  6. 25 tungsten probe tips with 2.4 micron tip radius.  7. Dark enclosure to enable testing under dark and to provide EMF shielding with feedthroughs: triax to coax (at least 4).  Four micro positioners with force/sense cables to feedthroughs.  8. Vibration isolation stage supporting the whole setup.Further, gas lines for clean dry air should be provided along with pressure specs.  9. High magnification turret microscope in-lieu of stereomicroscope with objectives: 2.5x, 10x, 20x, 50x. The 50x objective should support a working distance of at least 10 mm, with provision for external fiber coupling with a user supplied beam splitter.  10. 1080p resolution camera attachment for the microscope with software.  11. A high-speed c-mount camera (EM-CCD camera,sCMOS or equivalent) with software should be quoted.  12. Feedthroughs: a) coax to coax (2), b) multimode optical fibers SMA905 (1), c) multimode optical fiber for coupling external light source (1), d) 1 thermal (Pt/Si diode) sensor to shielded twisted pair cable, e) camera o/p to HDMI, f) USB-A M/M to USB-A M/M. Additionally, two blanks for future integration of additional feedthroughs should be provided. If any / all of these feedthroughs are not provided, the bidder must provide an easily replaceable light tight blank for the missing feedthroughs, and provide a link to the specific feedthrough available from another source. The bidder must thus make certain that the user does not need to drill a hole in the enclosure to install addition to the lines.  11. Avacuum pump and any needed vacuum lines for the chuck. Alternately, pressure specs for vacuum lines must be provided in addition to the lines.		elevator at present.	
<ol> <li>Probe card holder upgrade.</li> <li>Eight micro positioners for simultaneous use.</li> <li>25 tungsten probe tips with 6 micron tip radius.</li> <li>25 tungsten probe tips with 1.2 micron tip radius.</li> <li>25 tungsten probe tips with 2.4 micron tip radius.</li> <li>Dark enclosure to enable testing under dark and to provide EMF shielding with feedthroughs: triax to coax (at least 4).</li> <li>Four micro positioners with force/sense cables to feedthroughs.</li> <li>Vibration isolation stage supporting the whole setup. Further, gas lines for clean dry air should be provided along with pressure specs.</li> <li>High magnification turret microscope in-lieu of stereomicroscope with objectives: 2.5x, 10x, 20x, 50x. The 50x objective should support a working distance of at least 10 mm, with provision for external fiber coupling with a user supplied beam splitter.</li> <li>10. 1080p resolution camera attachment for the microscope with software.</li> <li>A high-speed c-mount camera (EM-CCD camera,sCMOS or equivalent) with software should be quoted.</li> <li>Feedthroughs: a) coax to coax (2), b) multimode optical fibers SMA905 (1), c) multimode optical fiber for coupling external light source (1), d) 1 thermal (Pt/Si diode) sensor to shielded twisted pair cable, e) camera o/p to HDMI, f) USB-A M/M to USB-A M/M. Additionally, two blanks for future integration of additional feedthroughs should be provided. If any / all of these feedthroughs are not provided, the bidder must provide an easily replaceable light tight blank for the missing feedthroughs, and provide a link to the specific feedthrough available from another source. The bidder must thus make certain that the user does not need to drill a hole in the enclosure to install additional feedthroughs.</li> <li>Vacuum pump and any needed vacuum lines for the chuck. Alternately, pressure specs for vacuum lines must be provided in addition to the lines.</li> </ol>		List of optional items	
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<ol> <li>25 tungsten probe tips with 2.4 micron tip radius.</li> <li>Dark enclosure to enable testing under dark and to provide EMF shielding with feedthroughs: triax to coax (at least 4).</li> <li>Four micro positioners with force/sense cables to feedthroughs.</li> <li>Vibration isolation stage supporting the whole setup. Further, gas lines for clean dry air should be provided along with pressure specs.</li> <li>High magnification turret microscope in-lieu of stereomicroscope with objectives: 2.5x, 10x, 20x, 50x. The 50x objective should support a working distance of at least 10 mm, with provision for external fiber coupling with a user supplied beam splitter.</li> <li>10. 1080p resolution camera attachment for the microscope with software.</li> <li>A high-speed c-mount camera (EM-CCD camera,sCMOS or equivalent) with software should be quoted.</li> <li>Feedthroughs: a) coax to coax (2), b) multimode optical fibers SMA905 (1), c) multimode optical fiber for coupling external light source (1), d) 1 thermal (Pt/Si diode) sensor to shielded twisted pair cable, e) camera o/p to HDMI, f) USB-A M/M to USB-A M/M. Additionally, two blanks for future integration of additional feedthroughs should be provided. If any / all of these feedthroughs are not provided, the bidder must provide an easily replaceable light tight blank for the missing feedthroughs, and provide a link to the specific feedthrough available from another source. The bidder must thus make certain that the user does not need to drill a hole in the enclosure to install additional feedthroughs.</li> <li>Vacuum pump and any needed vacuum lines for the chuck. Alternately, pressure specs for vacuum lines must be provided in addition to the lines.</li> </ol>	4.	25 tungsten probe tips with 6 micron tip radius.	
<ol> <li>Dark enclosure to enable testing under dark and to provide EMF shielding with feedthroughs: triax to coax (at least 4).</li> <li>Four micro positioners with force/sense cables to feedthroughs.</li> <li>Vibration isolation stage supporting the whole setup.Further, gas lines for clean dry air should be provided along with pressure specs.</li> <li>High magnification turret microscope in-lieu of stereomicroscope with objectives: 2.5x, 10x, 20x, 50x. The 50x objective should support a working distance of at least 10 mm, with provision for external fiber coupling with a user supplied beam splitter.</li> <li>10. 1080p resolution camera attachment for the microscope with software.</li> <li>A high-speed c-mount camera (EM-CCD camera,sCMOS or equivalent) with software should be quoted.</li> <li>Feedthroughs: a) coax to coax (2), b) multimode optical fibers SMA905 (1), c) multimode optical fiber for coupling external light source (1), d) 1 thermal (Pt/Si diode) sensor to shielded twisted pair cable, e) camera o/p to HDMI, f) USB-A M/M to USB-A M/M. Additionally, two blanks for future integration of additional feedthroughs should be provided. If any / all of these feedthroughs are not provided, the bidder must provide an easily replaceable light tight blank for the missing feedthroughs, and provide a link to the specific feedthrough available from another source. The bidder must thus make certain that the user does not need to drill a hole in the enclosure to install additional feedthroughs.</li> <li>Vacuum pump and any needed vacuum lines for the chuck. Alternately, pressure specs for vacuum lines must be provided in addition to the lines.</li> </ol>	5.	25 tungsten probe tips with 1.2 micron tip radius.	
feedthroughs: triax to coax (at least 4).  Four micro positioners with force/sense cables to feedthroughs.  8. Vibration isolation stage supporting the whole setup. Further, gas lines for clean dry air should be provided along with pressure specs.  9. High magnification turret microscope in-lieu of stereomicroscope with objectives: 2.5x, 10x, 20x, 50x. The 50x objective should support a working distance of at least 10 mm, with provision for external fiber coupling with a user supplied beam splitter.  10. 1080p resolution camera attachment for the microscope with software.  11. A high-speed c-mount camera (EM-CCD camera, sCMOS or equivalent) with software should be quoted.  12. Feedthroughs: a) coax to coax (2), b) multimode optical fibers SMA905 (1), c) multimode optical fiber for coupling external light source (1), d) 1 thermal (Pt/Si diode) sensor to shielded twisted pair cable, e) camera o/p to HDMI, f) USB-A M/M to USB-A M/M. Additionally, two blanks for future integration of additional feedthroughs should be provided. If any / all of these feedthroughs are not provided, the bidder must provide a link to the specific feedthrough available from another source. The bidder must thus make certain that the user does not need to drill a hole in the enclosure to install additional feedthroughs.  13. Vacuum pump and any needed vacuum lines for the chuck. Alternately, pressure specs for vacuum lines must be provided in addition to the lines.	6.	25 tungsten probe tips with 2.4 micron tip radius.	
<ul> <li>8. Vibration isolation stage supporting the whole setup. Further, gas lines for clean dry air should be provided along with pressure specs.</li> <li>9. High magnification turret microscope in-lieu of stereomicroscope with objectives: 2.5x, 10x, 20x, 50x. The 50x objective should support a working distance of at least 10 mm, with provision for external fiber coupling with a user supplied beam splitter.</li> <li>10. 1080p resolution camera attachment for the microscope with software.</li> <li>11. A high-speed c-mount camera (EM-CCD camera,sCMOS or equivalent) with software should be quoted.</li> <li>12. Feedthroughs: a) coax to coax (2), b) multimode optical fibers SMA905 (1), c) multimode optical fiber for coupling external light source (1), d) 1 thermal (Pt/Si diode) sensor to shielded twisted pair cable, e) camera o/p to HDMI, f) USB-A M/M to USB-A M/M. Additionally, two blanks for future integration of additional feedthroughs should be provided. If any / all of these feedthroughs are not provided, the bidder must provide an easily replaceable light tight blank for the missing feedthroughs, and provide a link to the specific feedthrough available from another source. The bidder must thus make certain that the user does not need to drill a hole in the enclosure to install additional feedthroughs.</li> <li>13. Vacuum pump and any needed vacuum lines for the chuck. Alternately, pressure specs for vacuum lines must be provided in addition to the lines.</li> </ul>	7.	feedthroughs: triax to coax (at least 4).	
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	I have	•	g pages.

	Signature of Bidder
Name:	
<b>Designation:</b>	

<b>Organization Name:</b>	
Contact No. :	

# << Organization Letter Head >> DECLARATION SHEET

We,	hereby certify that all the information and data furnished by
gone through the specification, conditions and	ification are true and complete to the best of our knowledge. I have stipulations in details and agree to comply with the requirements
and intent of specification.	
This is certified that our organization has been a	authorized (Copy attached) by the OEM to participate in Tender.We
further certified that our organization meets	all the conditions of eligibility criteria laid down in this tender
document. Moreover, OEM has agreed to supp	port on regular basis with technology / product updates and extend
support for the warranty.	
The prices quoted in the financial bids are subsi	dized due to academic discount given to IIT Delhi.
We, further specifically certify that our	NAME & ADDRESS OF
organization has not been Black Listed/De	THE Vendor/ Manufacturer / Agent
Listed or put to any Holiday by any Institutional	
Agency/ Govt. Department/ Public Sector	
Undertaking in the last three years.  1 Phone	
2 Fax	
3 E-mail	
4 Contact Person Name	
5 Mobile Number	
6 TIN Number	
7 PAN Number	
(In case of on-line payment of Tender Fees)	
8 UTR No. (For Tender Fee)	
(In case of on-line payment of EMD)	
9 UTR No. (For EMD)	
10 Kindly provide bank details of the	
bidder in the following format:	
a) Name of the Bank	

(Signature of the Tenderer)

Name:

**Seal of the Company** 

b) Account Number

c) Kindly attach scanned copy of one Chequebook page to enable us to return

the EMD to unsuccessful bidder

# **Annexure-III**

# List of Govt. Organization/Deptt.

List of Government Organizations for whom years (must be supported with work orders)	the Bidder has undertaken such wo	ork during last three
Name of the organization	Name of Contact Person	Contact No.
Name of application specialist / Service Engin		tency to handle and
support the quoted product during the warran Name of the organization	Name of Contact Person	Contact No.
Traine of the organization	Traine of Contact I croon	Contact 140.
		Signature of Bidden
	Name:	
	Organization Name:	
	<b>Contact No.:</b>	

# **Bid Submission**

# **Online Bid Submission:**

The Online bids (complete in all respect) must be uploaded onlineintwo Envelops as explained below:-

Sl. No.	Documents	Content	File Types			
1.	Technical Bid	Compliance Sheet as per Annexure - I	.PDF			
2.		Organization Declaration Sheet as per Annexure - II	.PDF			
3.		List of organizations/ clients where the same products have been supplied (in last two years) along with their contact number(s). (Annexure-III)	.PDF			
4. Technical supporting documents in support of all claims made at Annexure-I (Annexure-IV)		.PDF				
Envelope – 2						
Sl. No.	TYPES	Content				
1.	Financial Bid	Price bid should be submitted in PDF format.	.PDF			

# <Department/Centre Name> Indian Institute of Technology Delhi HauzKhas, New Delhi-110016

**Date: XX/XX/XXXX** 

# **Subject:Purchase of <Item> (Following format is used for imported items)**

S.	Currency	Description and Specification of	Qty.	Unit	Agency	Discount	Ex-works	Packing +	FOB/FCA	Insurance	CIF Price
No.		the Item	in	Price	Commission		price	Handling	Price	+ Freight	(f+g)
			Units		(If		(d=a+b-c)	+ DOC +	(f=d+e)	(g)	
				(a)	applicable)	(c)		Inland			
					(b)			Freight +			
								FCA			
								Charges			
								(e)			
1											

For indigenous items please quote as per following format.

S.	Description and Specification of the	Unit Price in	Excise Duty %	CST/VAT%	Octroi%	Total Price in
No.	Item	Rs.				Rs.
1.						
2.						

**Note**: The above financial template should be strictly followed. Any deviation from the above template (in terms of description and specification of the item) may lead to cancellation of the tender.